有铅

Sn62.9/Pb36.9/Ag0.2, Sn60/Pb39.9/Ag0.1, Sn62.8/Pb 36.8/Ag0.4, Sn63 /Pb36.9/Ag0.1,Sn55/Pb44.9/Ag0.1

1 0.4mm

2 12

3

4

5

“ --- ” “ ”

6 PCB

7 ICT

8 Paste in hole

		ROL1	J-STD-004
		0.2wt%	
(SIR)		$1 \times 10^{13}\ \Omega$	25mil
		$1 \times 10^{12}\ \Omega$	40 90%RH 96Hrs
		$1 \times 10^{5}\ \Omega$	
			IPC-TM-650
			IPC-TM-650
			In house

		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		200 Pa.s ±10% Malcolm (10rpm,25)	T3,90%metal for printing
		80 Pa.s±10% Malcolm (10rpm,25)	T4,87%metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate(Sn63,90%metal)
			J-STD-005
			In house
Vs		48gF 0	IPC-TM-650 ± 5%
		56gF 2	
		68gF 4	
		44gF 8	
		12	In house
			0~10

1. 如何选取用本系列锡膏

T3 mesh –325/+500 25~45 μ m

Fine pitch

2 使用前的准备

1) “ ”

0~10 “ ”

200 “ ”

4

“ ” “ ”

2)

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3 印刷

大量的事实表明，超过半数的焊接不良问题都与印刷部分有关，故需特别注意。

➢

有铅免洗

0.4mm

0.12mm

➢

➢

有铅免洗 80%

	60 ~ 90HS
	45^0 ~ 60^0
	2 ~ 4 × 10^5pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%

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